

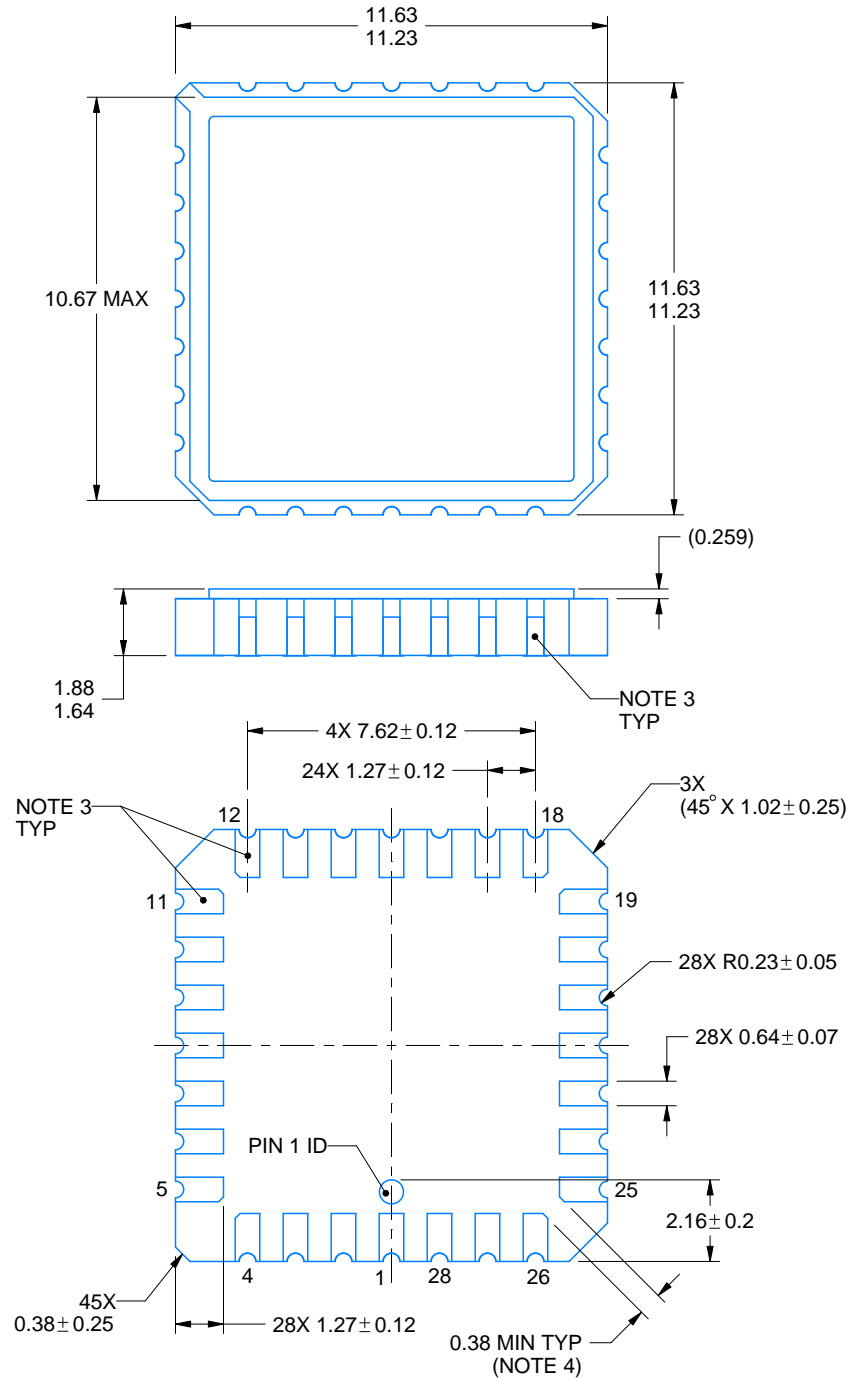
FK0028A



PACKAGE OUTLINE

LCCC - 1.88 mm max height

LEADLESS CERAMIC CHIP CARRIER



4214746/A 07/2022

NOTES:

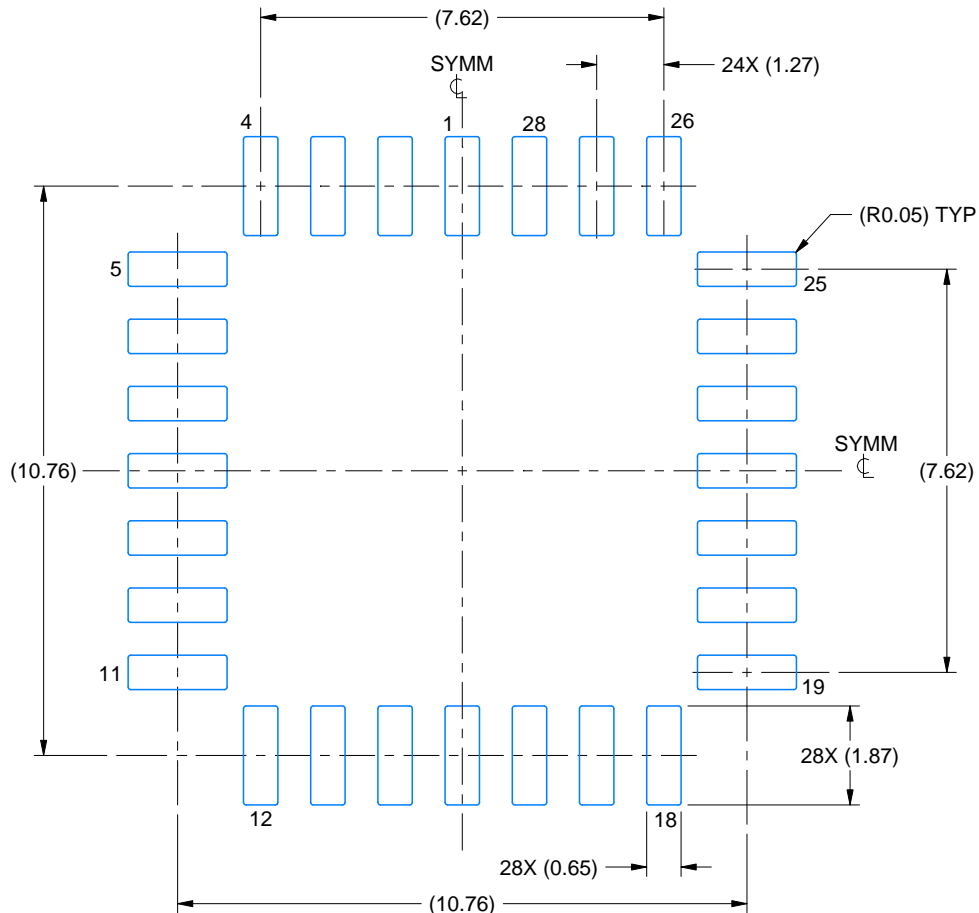
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The terminals are gold-plated.
4. Corner Pads may have a 45° X 0.51mm Maximum chamfer to accomplish 0.38mm dimension
5. Reference JEDEC Registration MS-014, Variation CC

# EXAMPLE BOARD LAYOUT

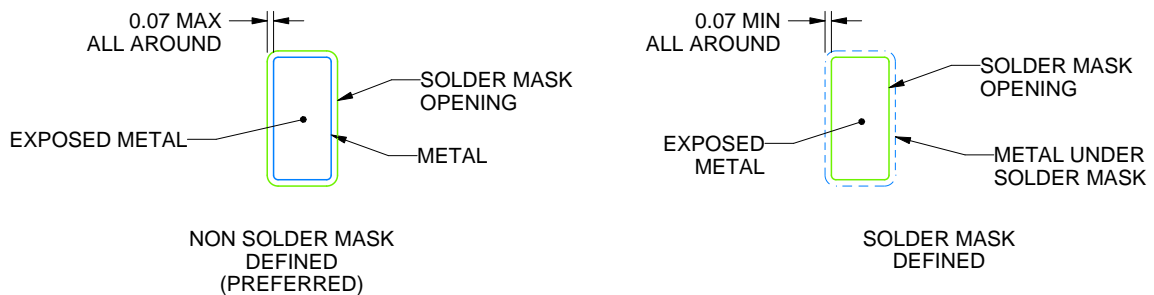
FK0028A

LCCC - 1.88 mm max height

LEADLESS CERAMIC CHIP CARRIER



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 7X



SOLDER MASK DETAILS  
NOT TO SCALE

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NOTES: (continued)

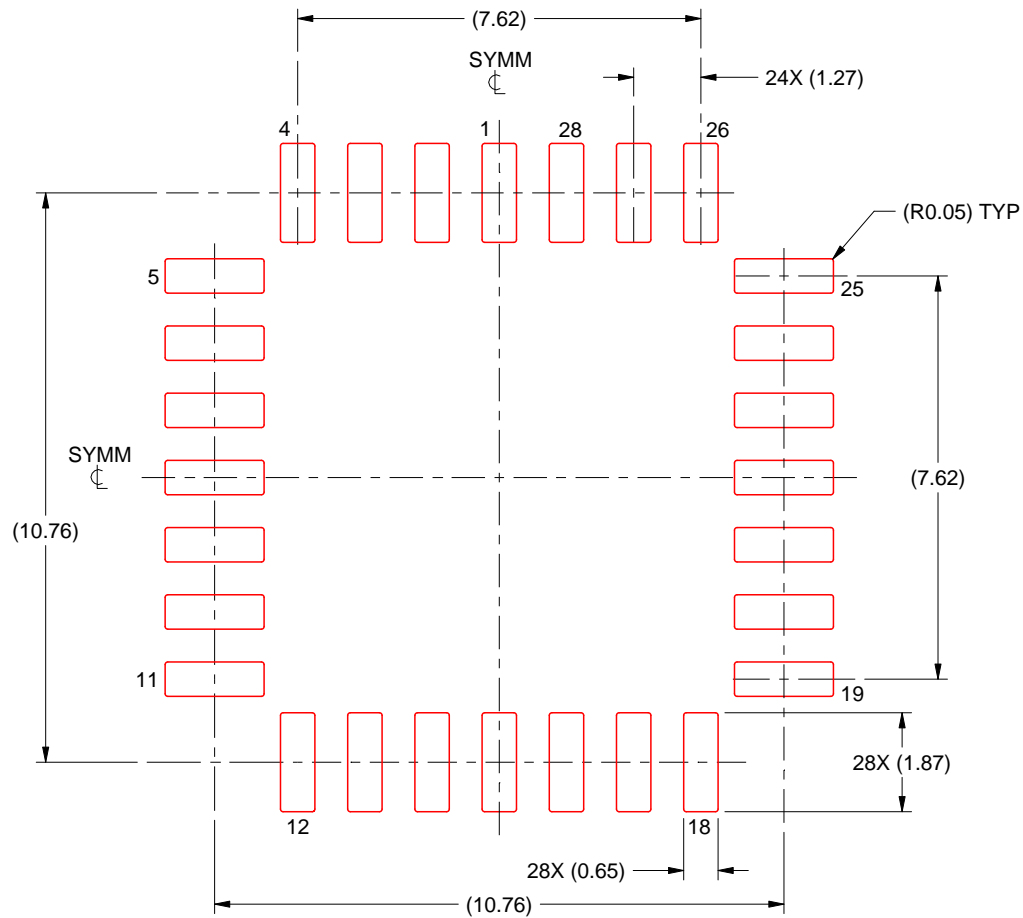
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

FK0028A

LCCC - 1.88 mm max height

LEADLESS CERAMIC CHIP CARRIER



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 7X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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